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(71)Applicant : **KYOCERA CORP**

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(54) WIRING BOARD AND ITS MANUFACTURE

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a wiring board capable of high density formation of viahole conductors by improving insulation reliability between neighboring viahole conductors.

SOLUTION: An insulating board 4 is formed by impregnating woven fabric 2 or unwoven fabric formed of glass fiber 8 with thermosetting resin 3, and penetrating holes 5 are formed in the board 4. In a wiring board 1 having viahole conductors 6 formed by filling the penetrating holes 5 with conductive paste containing metal powder, end portions of the glass fiber 8 exposed on the wall surface of the viahole conductors 6 form lumps 9 having a minimum diameter larger than or equal to 1.2 times the diameter of the glass fiber 8. The boundary part between the glass fiber 8 and the thermosetting resin 3 on the viahole conductor 6 wall surface is sealed with the lumps 9.

